

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	336	li-jin\$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 13:52
S2	2	li-jin\$.in. and (microlens)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 13:53
S3	268	(257/294).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 13:53
S4	244	S3 and (@ad<"20030903")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 13:53
S5	37	S3 and (@ad<"20030903") and (microlens)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:01
S6	4381	(257/44,431,432,440,233,234).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:01
S7	142	S6 and (@ad<"20030903") and (microlens) not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:48
S8	1	S6 and (@ad<"20030903") and ((chemical adj mechanical adj polishing) with (chemical adj etching or (reactive adj ion adj etching)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:53

S9	1412269	(semiconductor) and (@ad<"20030903") (recess\$2) and ((chemical adj mechanical adj polishing) with (chemical adj etching or (reactive adj ion adj etching)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:53
S10	7	(semiconductor) and (@ad<"20030903") and ((recess\$2) with ((chemical adj mechanical adj polishing) with (chemical adj etching or (reactive adj ion adj etching))))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:55
S11	1	(semiconductor) and (@ad<"20030903") and ((recess\$2) with ((chemical adj mechanical adj polishing) with (chemical adj etching )))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 14:55